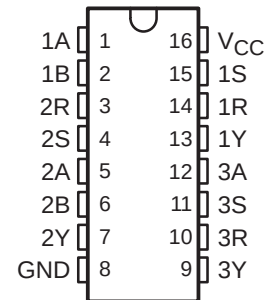


- Meets or Exceeds the Requirements of IBM™ System 360 Input/Output Interface Specification
- Operates From Single 5-V Supply
- TTL Compatible
- Built-In Input Threshold Hysteresis
- High Speed . . . Typical Propagation Delay Time = 20 ns
- Independent Channel Strobes
- Input Gating Increases Application Flexibility
- Designed for Use With Dual Line Driver SN75123
- Designed to Be Interchangeable With Signetics N8T24

D OR N PACKAGE
(TOP VIEW)



description

The SN75124 triple line receiver is specifically designed to meet the input/output interface specifications for IBM System 360. It is also compatible with standard TTL logic and supply voltage levels.

The SN75124 has receiver inputs with built-in hysteresis to provide increased noise margin for single-ended systems. An open line affects the receiver input as does a low-level input voltage, and the receiver input can withstand a level of -0.15 V with power on or off. The other inputs are in TTL configuration. The S input must be high to enable the receiver input. Two of the line receivers have A and B inputs that, if both are high, hold the output low. The third receiver has only an A input that, if high, holds the output low.

See the SN751730 for new IBM 360/370 interface designs.

The SN75124 is characterized for operation from 0°C to 70°C .

FUNCTION TABLE

INPUTS				OUTPUT Y
A	B [†]	R	S	
H	H	X	X	L
X	X	L	H	L
L	X	H	X	H
L	X	X	L	H
X	L	H	X	H
X	L	X	L	H

[†] B input and last two lines of the function table are applicable to receivers 1 and 2 only.



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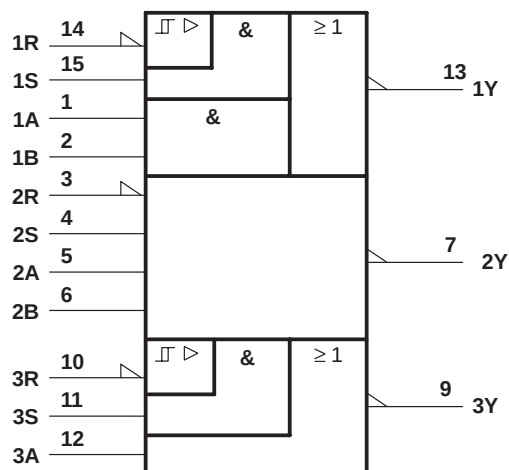
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SN75124

TRIPLE LINE RECEIVER

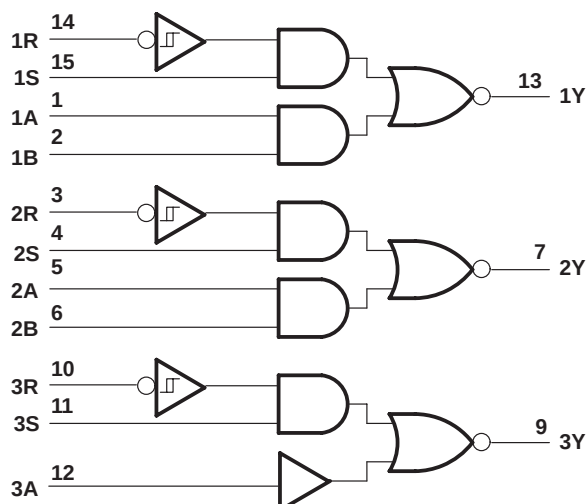
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logic symbol†

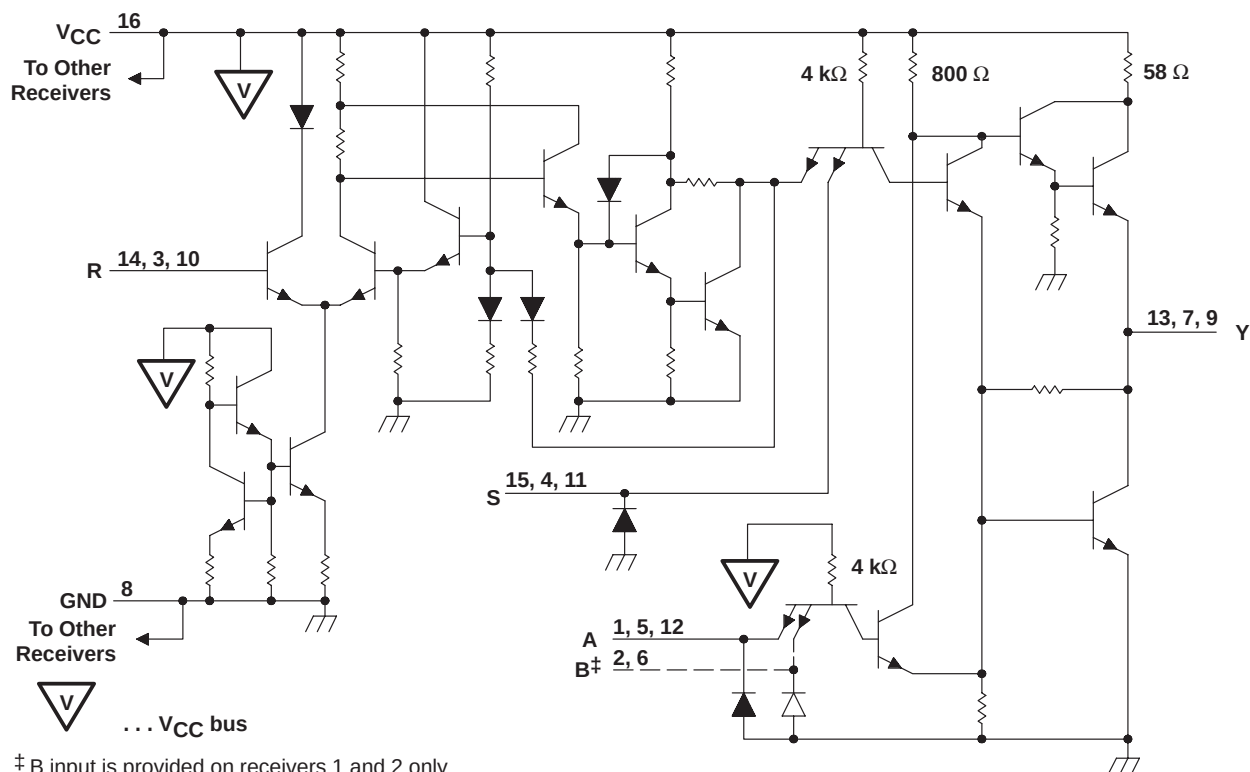


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic (each receiver)



‡ B input is provided on receivers 1 and 2 only
Resistor values shown are nominal.

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage, V_I : R input with V_{CC} applied	7 V
R input with V_{CC} not applied	6 V
A, B, or S input	5.5 V
Output voltage, V_O	7 V
Output current, I_O	± 100 mA
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTE 1: Voltage values are with respect to network ground terminal

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW
N	1150 mW	9.2 mW/°C	736 mW

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
High-level input voltage, V_{IH}	A, B, or S	2			V
	R	1.7			
Low-level input voltage, V_{IL}	A, B, or S	0.8			V
	R	0.7			
High-level output current, I_{OH}		−800			μA
Low-level output current, I_{OL}		16			mA
Operating free-air temperature, T_A		0	70		°C

SN75124
TRIPLE LINE RECEIVER

SLLS058B – SEPTEMBER 1973 – REVISED MAY 1995

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT–})	R	V _{CC} = 5 V, T _A = 25°C	0.2	0.5		V
V _{IK}	Input clamp voltage	A, B, or S	V _{CC} = 5 V, I _I = 12 mA			–1.5	V
V _{I(BR)}	Input breakdown voltage	A, B, or S	V _{CC} = 5 V, I _I = 10 mA	5.5			V
V _{OH}	High-level output voltage		V _{IH} = V _{IHmin} , I _{OH} = –800 μA, V _{IL} = V _{ILmax} , See Note 2	2.6			V
V _{OL}	Low-level output voltage		V _{IH} = V _{IHmin} , I _{OL} = 16 mA, V _{IL} = V _{ILmax} , See Note 2			0.4	V
I _I	Input current at maximum input voltage	R	V _I = 7 V			5	mA
			V _I = 6 V, V _{CC} = 0			5	
I _{IH}	High-level input current	A, B, or S	V _I = 4.5 V			40	μA
		R	V _I = 3.11 V			170	
I _{IL}	Low-level input current	A, B, or S	V _I = 0.4 V, V _{IR} = 0.8 V	–0.1		–1.6	mA
I _{OS}	Short-circuit output current†			–50		–100	mA
I _{CC}	Supply current		All inputs = 0.8 V			72	mA
			All inputs = 2 V			100	

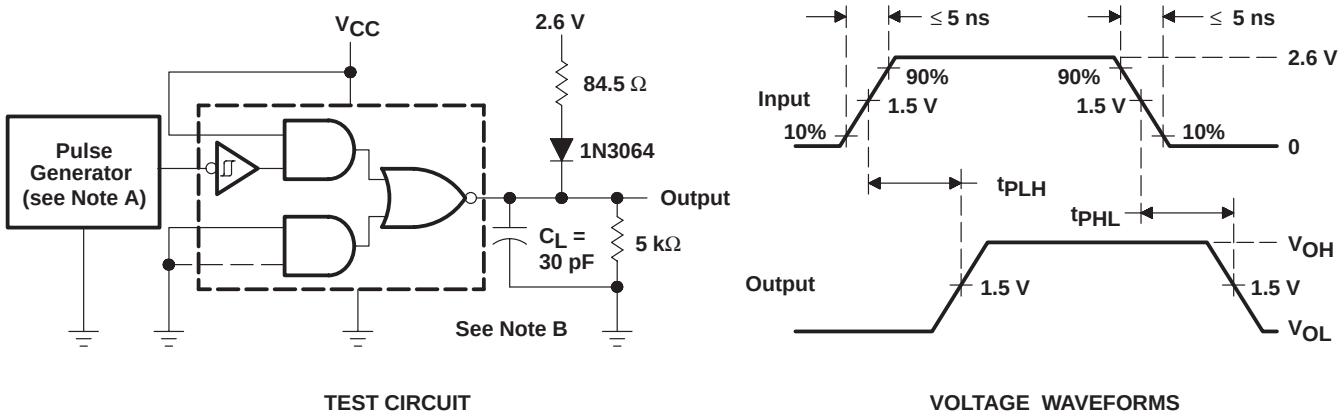
† Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

NOTE 2: The output voltage and current limits are characterized for any appropriate combination of high and low inputs specified by the function table for the desired output.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low-to-high-level output from R input	See Figure 1		20	30	ns
t _{PHL}	Propagation delay time, high-to-low-level output from R input			20	30	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: Z_O ≈ 50 Ω, PRR ≤ 5 MHz, duty cycle = 50%.
B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

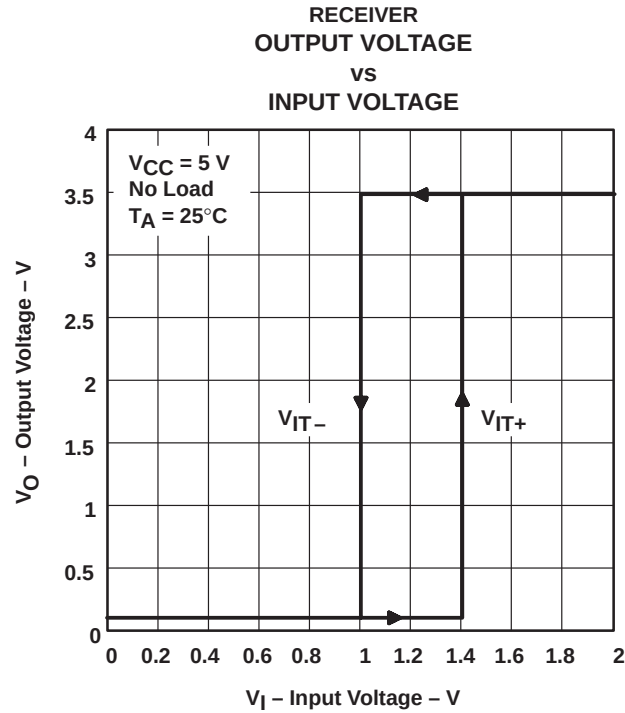


Figure 2

APPLICATION INFORMATION

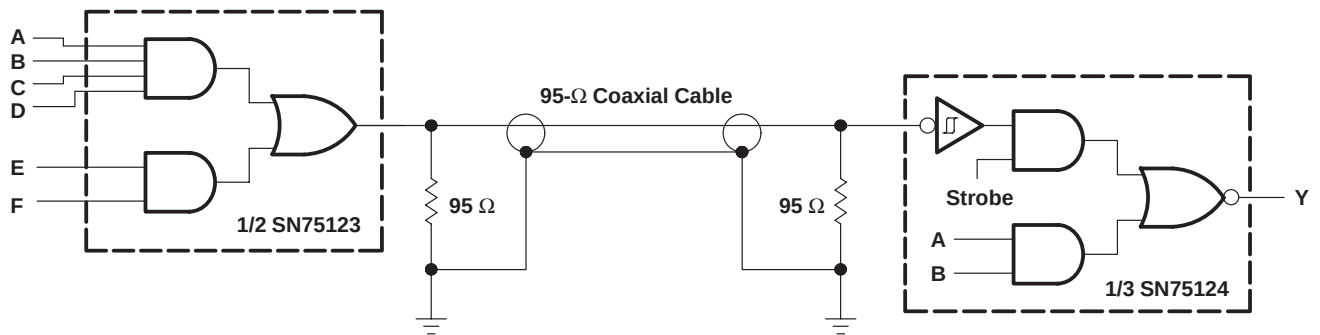


Figure 3. Unbalanced Line Communication Using SN75123 and SN75124

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN75124D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	Samples Not Available
SN75124N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
SN75124NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
SN75124NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN75124NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN75124NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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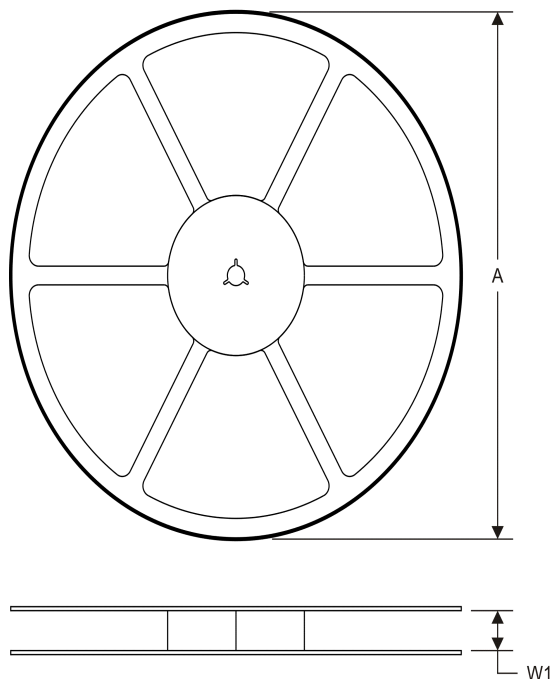
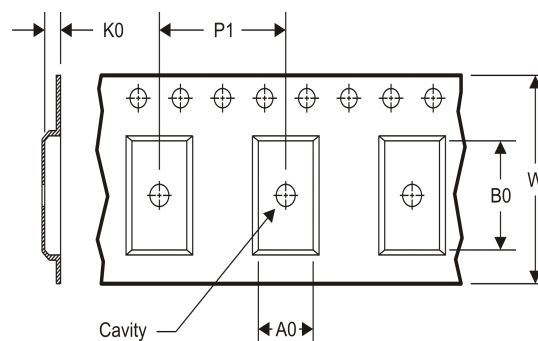


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PACKAGE OPTION ADDENDUM

7-Jun-2010

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


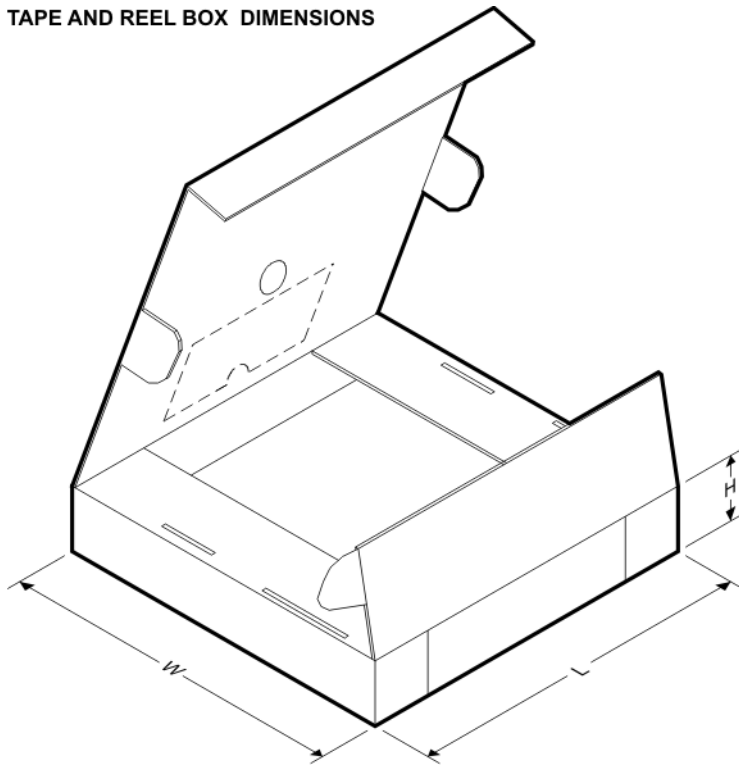
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75124NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



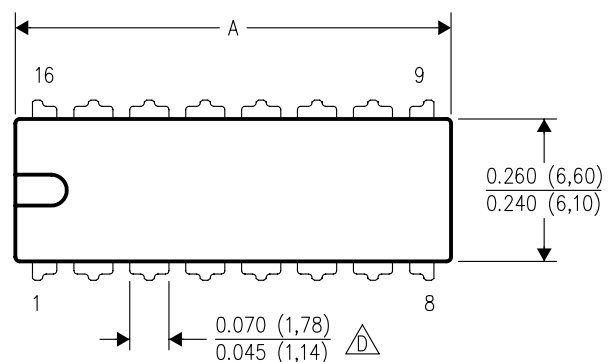
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75124NSR	SO	NS	16	2000	367.0	367.0	38.0

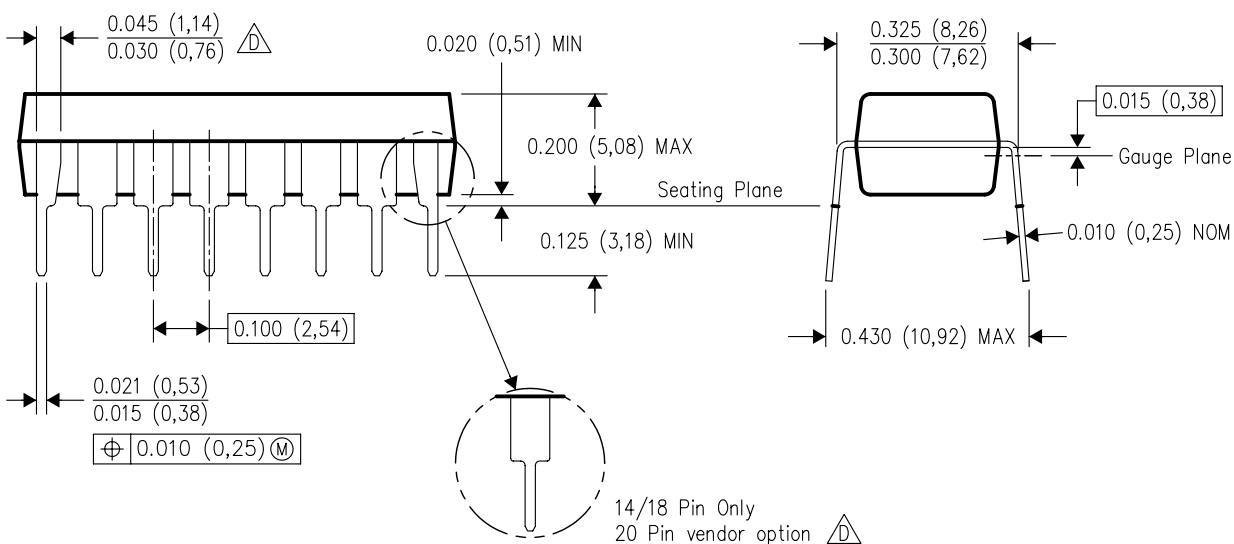
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



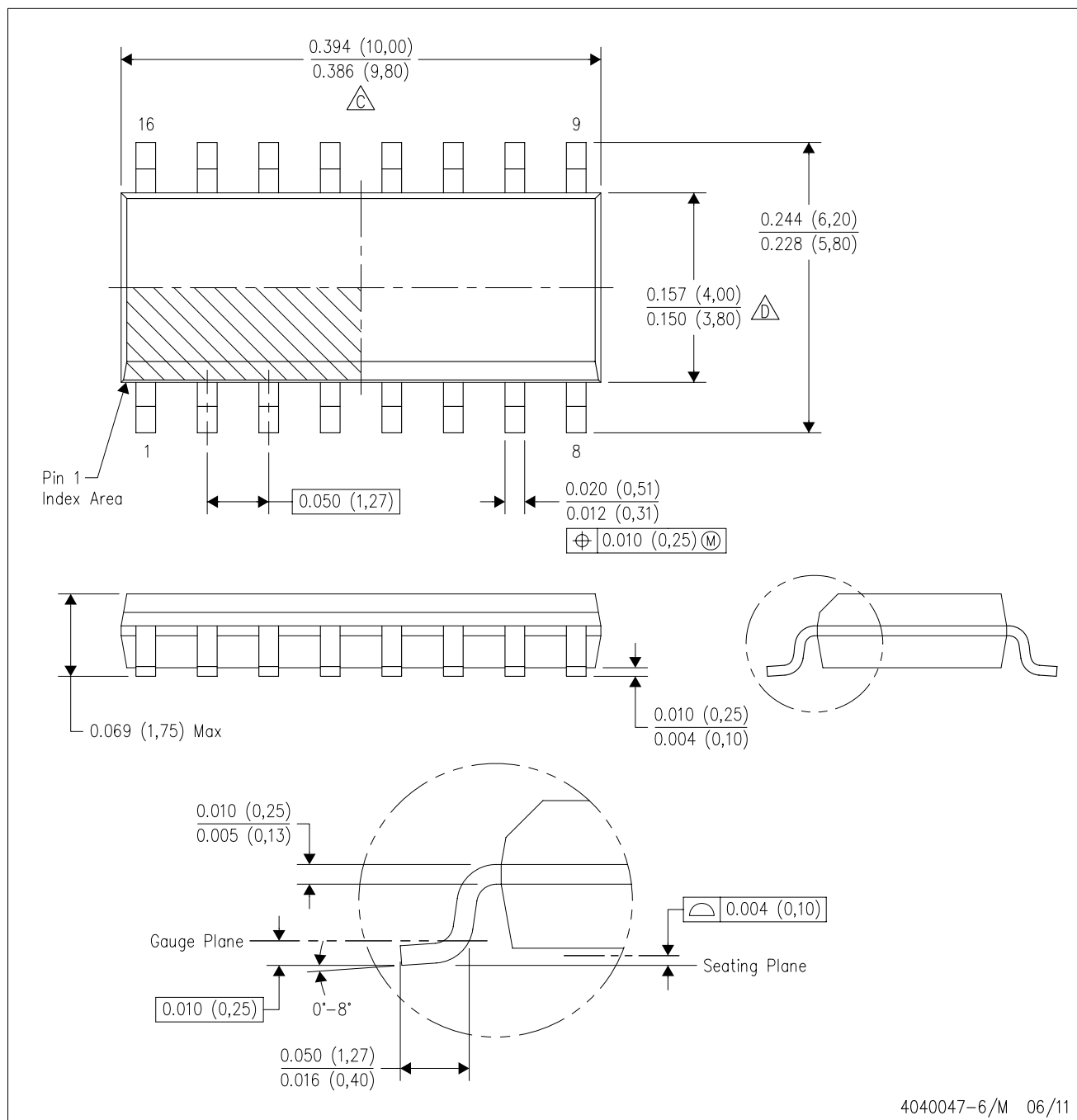
4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

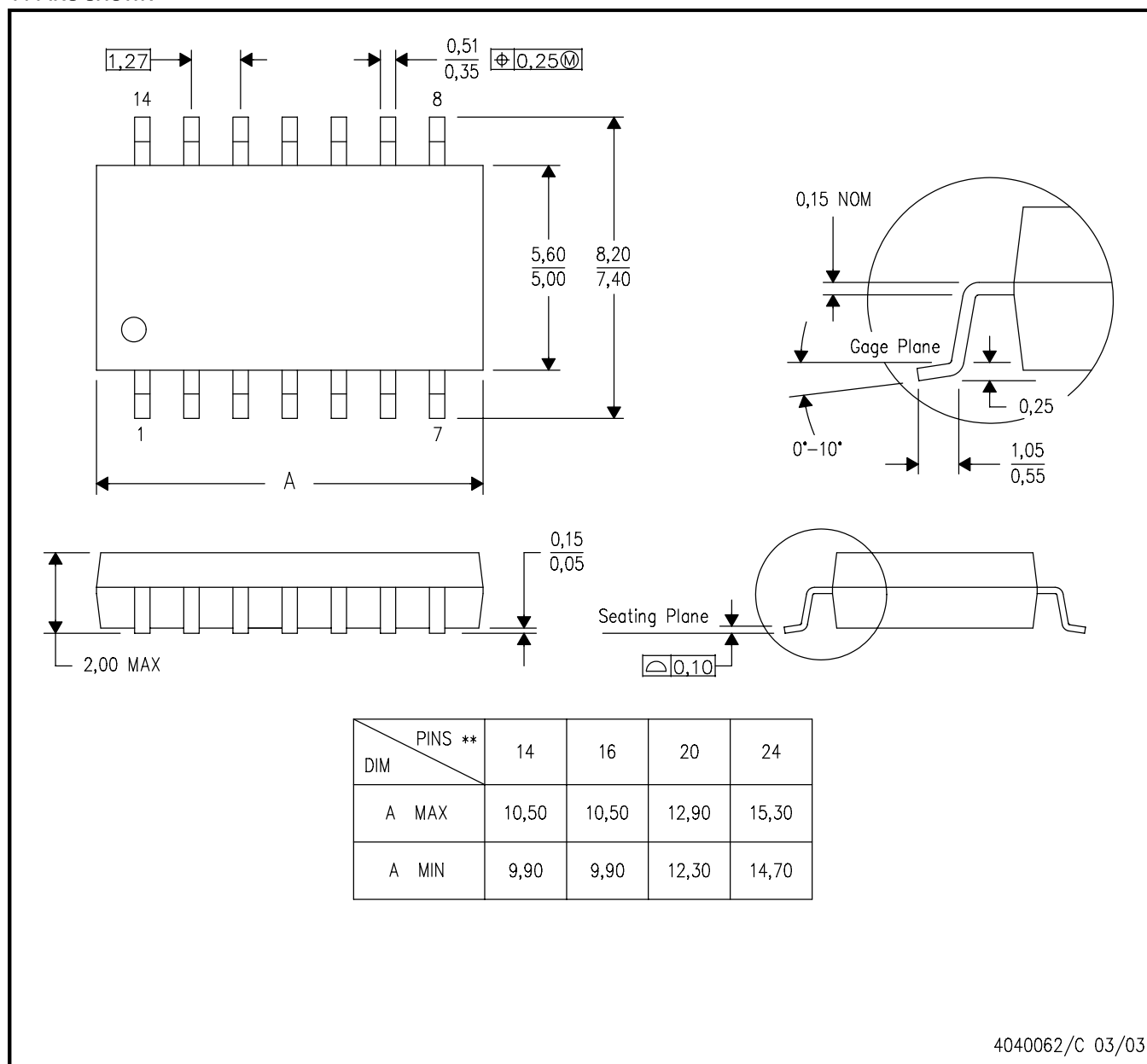
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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